

ENGINEERING DEPT.		PRODUCT SPECIFICATION For 2.54 mm (.100") Board to Board Connectors of System CB93	SPEC.NO.: SPCB039B
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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA - 364	Test methods for electrical connectors

3. APPLICABLE SERIES NO.: **CB93 Series**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

0.8 mm (.031") ~ 1.6 mm (.063")

REVIEWED : Eisley APPROVED : Eisley VERIFIED : Michelle .

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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		3AMP 250V AC(r.m.s)
7.2	Contact resistance	Dry circuit of 100 mA max.	Less than 30 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 1000 V between adjacent terminal or ground	More than 5000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Single contact insertion force	Measure force to insertion using 0.64 mm square pin at speed 25± 3 mm per minute	200 gram max.
8.2	Single contact withdrawal force	Measure force to withdrawal using 0.64 mm square pin at speed 25± 3 mm per minute	30 gram min.

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Vibration	1.5 mm 10 - 55 - 10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.2	Solder ability	Soldering time: 5 ± 0.5 second Soldering pot: 245 ± 5 °C	Minimum: 95% of immersed area
9.3	Resistance to soldering heat	Lead-Free Process Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5 °C	No damage
9.4	Temperature Life	Heat: 105± 2 °C, 96 hours Cold: -55± 2 °C, 96 hours	No damage Contact resistance: Less than twice of initial

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	ITEM	TEST CONDITION	REQUIREMENT
9.5	Humidity	40±2 °C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Insulation resistance more than 100 MΩ Dielectric strength: To pass para 7-3
9.6	Temperature cycling	One cycle consists of : (1) -55 ⁺⁰ / ₋₃ °C , 30 min. (2) Room temp. 10-15 min. (3) 105 ⁺³ / ₋₀ °C , 30 min. (4) Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.7	Salt spray	Temperature: 35 ± 3 °C Solution: 5 ± 1% Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE: -55°C ~ + 105°C